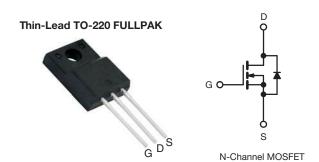


Vishay Siliconix

E Series Power MOSFET



PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	550)
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V	0.184
Q _g max. (nC)	92	
Q _{gs} (nC)	10	
Q _{gd} (nC)	19	
Configuration	Sing	le

FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>



APPLICATIONS

- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting
- Consumer electronics
- · Applications using hard switched topologies
 - Power factor correction (PFC)
 - Two switch forward converter
 - Flyback converter
- Switch mode power supplies (SMPS)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA20N50E-E3
Lead (Pb)-free and halogen-free	SiHA20N50E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	less otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	500	V	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T,I = 150 °C) e	V -+ 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		19		
Continuous drain current (1) = 150 C)	V _{GS} at 10 V	T _C = 100 °C	I _D	12	Α	
Pulsed drain current ^a			I _{DM}	42		
Linear derating factor				1.4	W/°C	
Single pulse avalanche energy b			E _{AS}	204	mJ	
Maximum power dissipation			P_{D}	34	W	
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C			
Drain-source voltage slope	V _{DS} = 0 V to 80 % V _{DS}		70		V/ns	
Reverse diode dV/dt ^d			dV/dt	32	V/fis	
Soldering recommendations (peak temperature) ^c	for	10 s		300	°C	
Mounting torque M3 screw				0.6	Nm	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.8 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, dI/dt = 100 A/µs, starting $T_J = 25 \,^{\circ}\text{C}$
- e. Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	3.7	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•			•	•	
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		500	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.59	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-source leakage	I_{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
Zoro goto voltago droin ourrent		V _{DS} =	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 400 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 10 A	-	0.160	0.184	Ω
Forward transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 10 A		-	4.4	-	S
Dynamic					-		•
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	1640	-	pF
Output capacitance	C _{oss}			-	87	-	
Reverse transfer capacitance	C _{rss}			-	6	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	73	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	222	-	
Total gate charge	Qg			-	46	92	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 10 A, V_{DS} = 400 V$	-	10	-	nC
Gate-drain charge	Q _{gd}	1		-	19	-	
Turn-on delay time	t _{d(on)}			-	17	34	
Rise time	t _r	$V_{DD} = 400 \text{ V}, I_{D} = 10 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	27	54	ns
Turn-off delay time	t _{d(off)}			-	48	96	
Fall time	t _f			-	25	50	
Gate input resistance	R _g	f = 1 MHz, open drain		-	0.83	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	19	,
Pulsed diode forward current	I _{SM}			-	-	42	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 10 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 10 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	293	-	ns
Reverse recovery charge	Q _{rr}			-	4.0	-	μC
Reverse recovery current	I _{RRM}			_	26	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

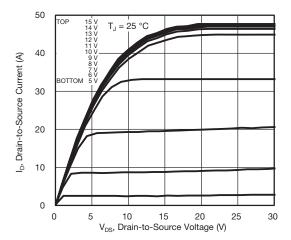


Fig. 1 - Typical Output Characteristics

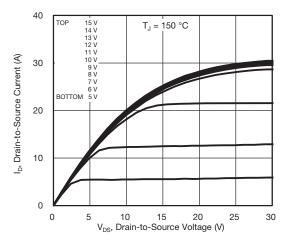


Fig. 2 - Typical Output Characteristics

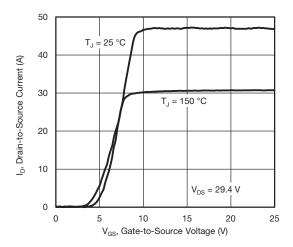


Fig. 3 - Typical Transfer Characteristics

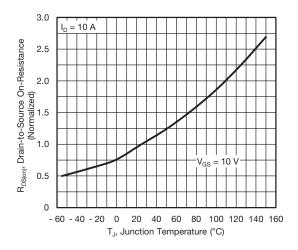


Fig. 4 - Normalized On-Resistance vs. Temperature

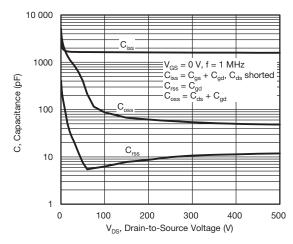


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

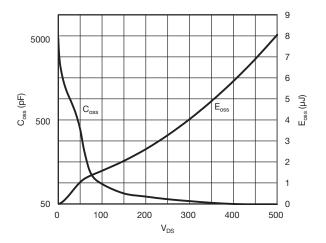


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



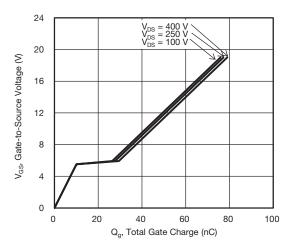


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

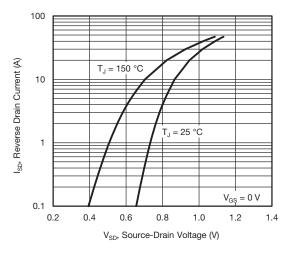


Fig. 8 - Typical Source-Drain Diode Forward Voltage

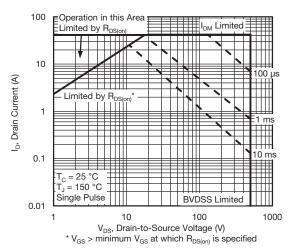


Fig. 9 - Maximum Safe Operating Area

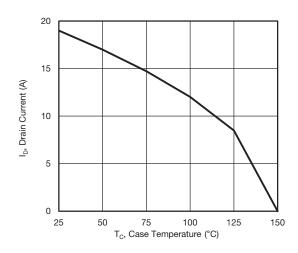


Fig. 10 - Maximum Drain Current vs. Case Temperature

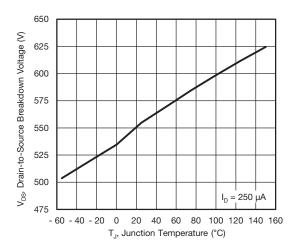


Fig. 11 - Temperature vs. Drain-to-Source Voltage



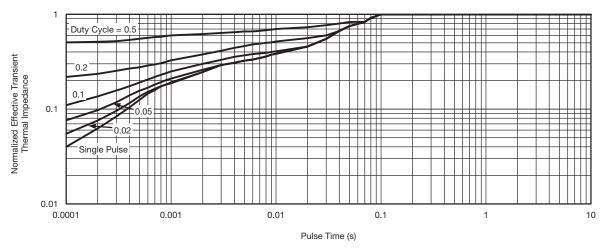


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

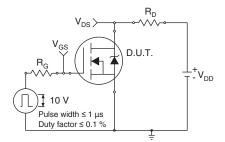


Fig. 13 - Switching Time Test Circuit

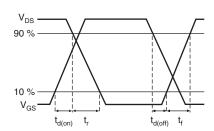


Fig. 14 - Switching Time Waveforms

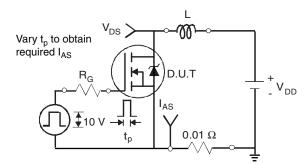


Fig. 15 - Unclamped Inductive Test Circuit

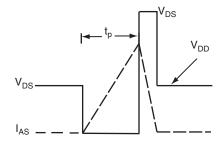


Fig. 16 - Unclamped Inductive Waveforms

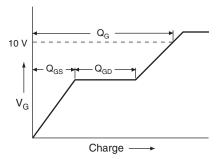


Fig. 17 - Basic Gate Charge Waveform

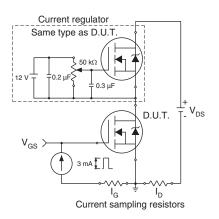
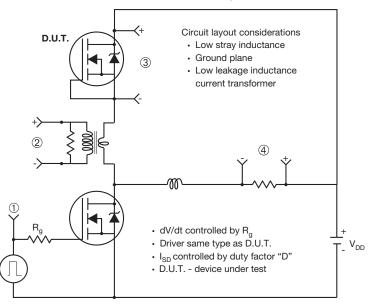


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



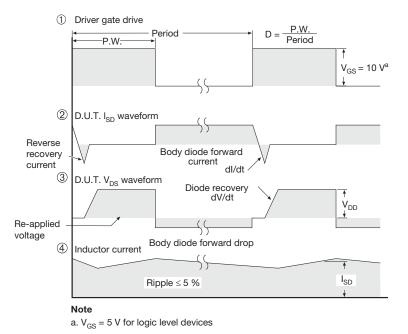
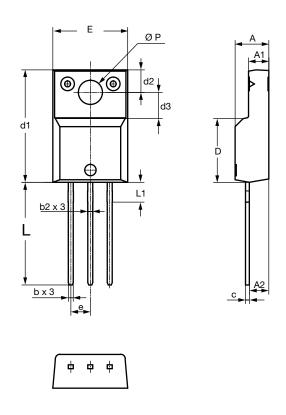


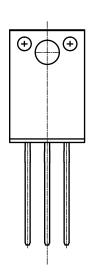
Fig. 19 - For N-Channel

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Vishay Siliconix

TO-220 FULLPAK Thin Lead





SYMBOL		DIMEN	ISIONS	
	MILLIN	IETERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
Α	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.40	2.80	0.094	0.110
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	=	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.30	3.70	0.130	0.146
Е	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	1.00	2.80	0.039	0.110
ØP	3.00	3.40	0.118	0.134

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



Vishay

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